classifying said extracted defect candidate image into a first category;

classifying said extracted defect candidate image into a second category; and

displaying on a screen said extracted defect candidate image and information relating to said classification into said first category and information relating to said classification into said second category.

2. The method for classifying defects as described in claim 1 wherein said imaging of said inspected object is performed by illuminating and scanning an electron beam focused on said inspected object and detecting, in synchronization with said scanning, secondary electrons generated from said inspected object by said illumination.

3. The method for classifying defects as described in claim 1 wherein said first category relates to defect criticality.

4. The method for classifying defects as described in claim 3 wherein said second category relates to defect type.

5. The method for classifying defects as described in claim 4 wherein said defect type includes one or more of the following: particle defects, flaw defects, circuit pattern short defects, and circuit pattern open defects.

6. A method for classifying defects comprising:

imaging an inspected object to obtain an image;

extracting an image of a defect candidate from said image obtained by said imaging step;

classifying said extracted defect candidate image into at least one defect type;

evaluating criticality of defect of said defect candidate image classified into said at least one defect type; and

displaying on a screen said defect candidate image along with information relating to the type of said at least defect type and said criticality of defect.

7. The method for classifying defects as described in claim 6 wherein said imaging of said inspected object is performed by illuminating and scanning an electron beam focused on said inspected object and detecting, in synchronization with said scanning, secondary electrons generated from said inspected object by said illumination.

8. The method for classifying defects as described in claim 6 wherein said defect types for classification include one or more of the following: particle defects, flaw defects, circuit pattern short defects, and circuit pattern open defects.

9. A method for classifying defects comprising:

imaging an inspected object;

extracting images of defect candidates from said inspected object;

classifying said extracted defect candidate images into a first category;

classifying said extracted defect candidate images into a second category, said second category relating to predicted yield from said inspected object; and

displaying on a single screen a distribution on said inspected object of said defect candidates classified in said first category and information relating to said first category classification and information relating to results of said second category classification.

10. The method for classifying defects as described in claim 9 wherein said imaging of said inspected object is performed by illuminating and scanning an electron beam focused on said inspected object and detecting, in synchronization with said scanning, secondary electrons generated from said inspected object by said illumination.

11. The method for classifying defects as described in claim 9 wherein an image of said defect candidate is also displayed on said screen.

23. The method for classifying defects as described in claim 2 further comprising forming an image based on said secondary electrons generated from said inspected object by said illumination.